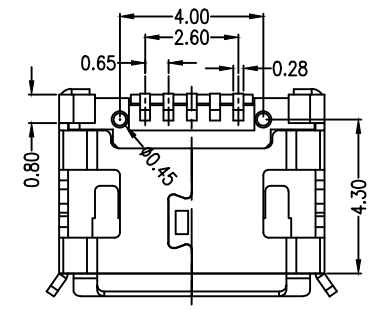
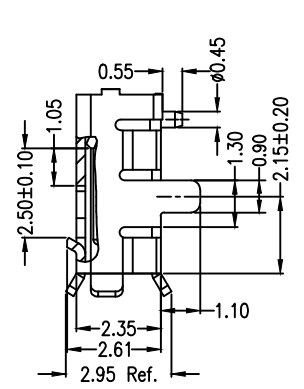
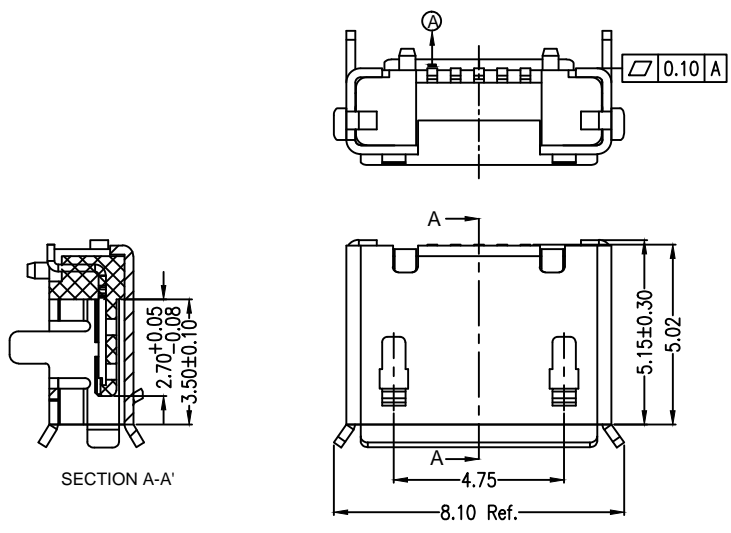
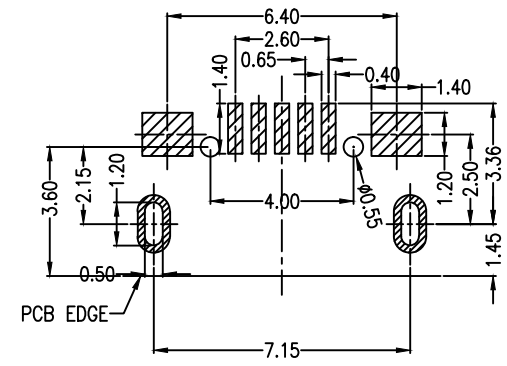
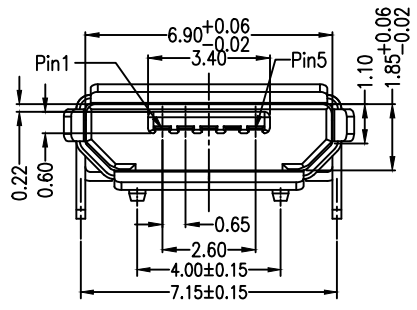


MAPX	MODIFICATION	DATE



- Note:
- Material:
    - Housing: High temperature thermoplastic with g.f,UL94v-0
    - Contact: copper alloy,t=0.20mm, contact area Au 15u" gold-plating, solder area Gold Flash. NICKEL UNDERPLATING OVER ALL 30U"
    - Shell: copper or sus304,t=0.25mm 50u" MIN. TIN(MATTE) PLATING.
  - Specification:
    - Current rating:1.5PIN 1.2A Max/2,3,4PIN 1A Max.
    - Dielectric withstanding voltage: 100 V(ac) for 1 min.
    - Contact resistance: 50 mΩ Max.
    - Insulation resistance: 100 MΩ Min.
    - Total mating force: 3.57 Kgf Max.
    - Total unmating force: 1.0 Kgf Min.
    - Temperature range: -30°C~80°C



RECOMMENDED PCB LAYOUT  
PCB图仅供参考

<b>产品图</b> PRODUCT CHART DWG		<b>易芯精密科技(浙江)有限公司</b> Easychips Precision Technology (Zhejiang) Co.,Ltd.			
<b>公差一览表</b> TOLERANCE UNLESS OTHERWISE		单位 UNITS	MM	制图 DRAWING	制图料号 PRODUCT PART NO.
X.	±0.30	X.	±5.°	比例 SCALE	产品名称 PRODUCT NO.
.X	±0.25	.X	±2.°		
.XX	±0.20	.XX	±1.°	日期 DATE	角法 VIEW
.XXX	±0.10	.XXX	±0.5°		
		日期 DATE	2019.11.23	审核 APPD	角法 VIEW
				角法 VIEW	版本 VER
				角法 VIEW	版本 VER

B920-ECA52A2021S10105  
 MICRO/5P-F 两脚DIP7.2有边脚长  
 1.1有柱加焊脚短端SMT  
 A0